Board Stack Report

Stack Up		Layer Stack																				
Layer	Board Layer Stack	Name	Material	Thickness	Constant	Dk	Df	Coverlay expansion	Color	Frequency	Solid	GlassTransTemp	Manufacturer	MaterialDescription	Description	Process	Orientation	Copper Orientation	Weight	Constructions	Resin	Pullback distance
1		Top Overlay		0mm																		
2		Top Solder	SM-001	0.0254mm	4	4	0.03	0mm	#FF008000	1GHz	1%	125°C	Altium Designer	Solder Mask	Solder Mask							
3		Top Surface Finish	Nickel, Gold	0.004mm					#FFFFC400							ENIG						
4		SIG L1	CF-004	0.035mm									Altium Designer	Copper Foil	Copper Foil	ED	BodyUp	Above	28.34952g			
5		PP1-2116	PP-017	0.105mm	4.3	4.3	0.02			1GHz		180°C	Altium Designer							2116	57%	
6		SIG L2	CF-004	0.035mm									Altium Designer	Copper Foil	Copper Foil	ED	None	Above	28.34952g			0.508mm
7		Core-FR4	Core-039	1.2mm	4.8	4.8	0.02			1GHz		180°C	Altium Designer	FR4						4-7628	40%	
8		SIG L3	CF-004	0.035mm									Altium Designer	Copper Foil	Copper Foil	ED	None	Below	28.34952g			0.508mm
9		PP2-2116	PP-017	0.105mm	4.3	4.3	0.02			1GHz		180°C	Altium Designer							2116	57%	
10		SIG L4	CF-004	0.035mm									Altium Designer	Copper Foil	Copper Foil	ED	BodyDown	Below	28.34952g			
11		Bottom Surface Finish	Nickel, Gold	0.004mm					#FFFFC400							ENIG						
12		Bottom Solder	SM-001	0.0254mm	4	4	0.03	0mm	#FF008000	1GHz	1%	125°C	Altium Designer	Solder Mask	Solder Mask							
13		Bottom Overlay		0mm																		
	Height : 1.60881mm																					